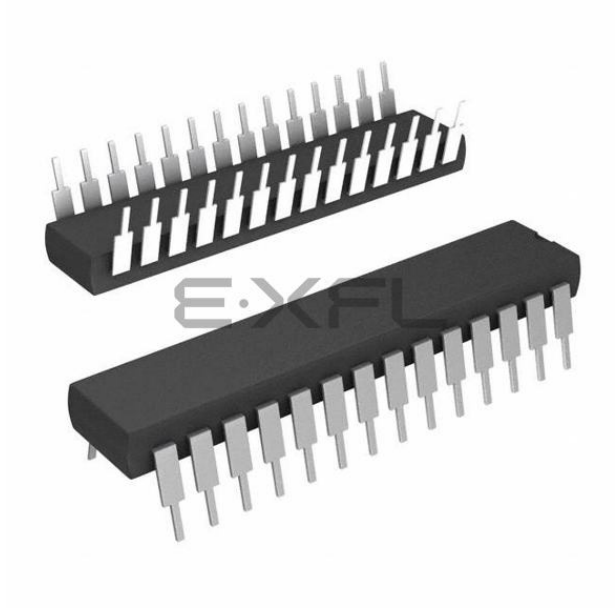

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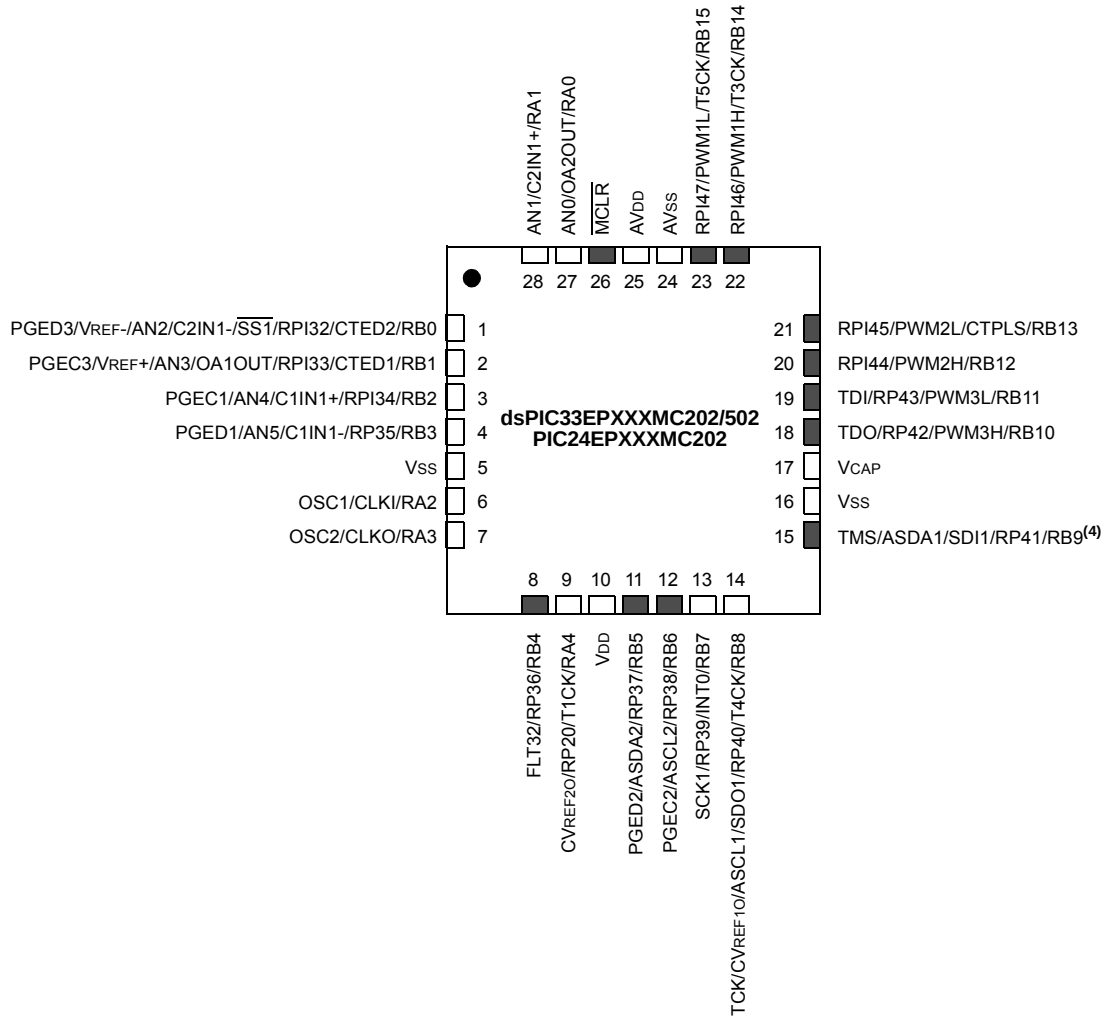
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gp502-e-sp

Pin Diagrams (Continued)

28-Pin QFN-S(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

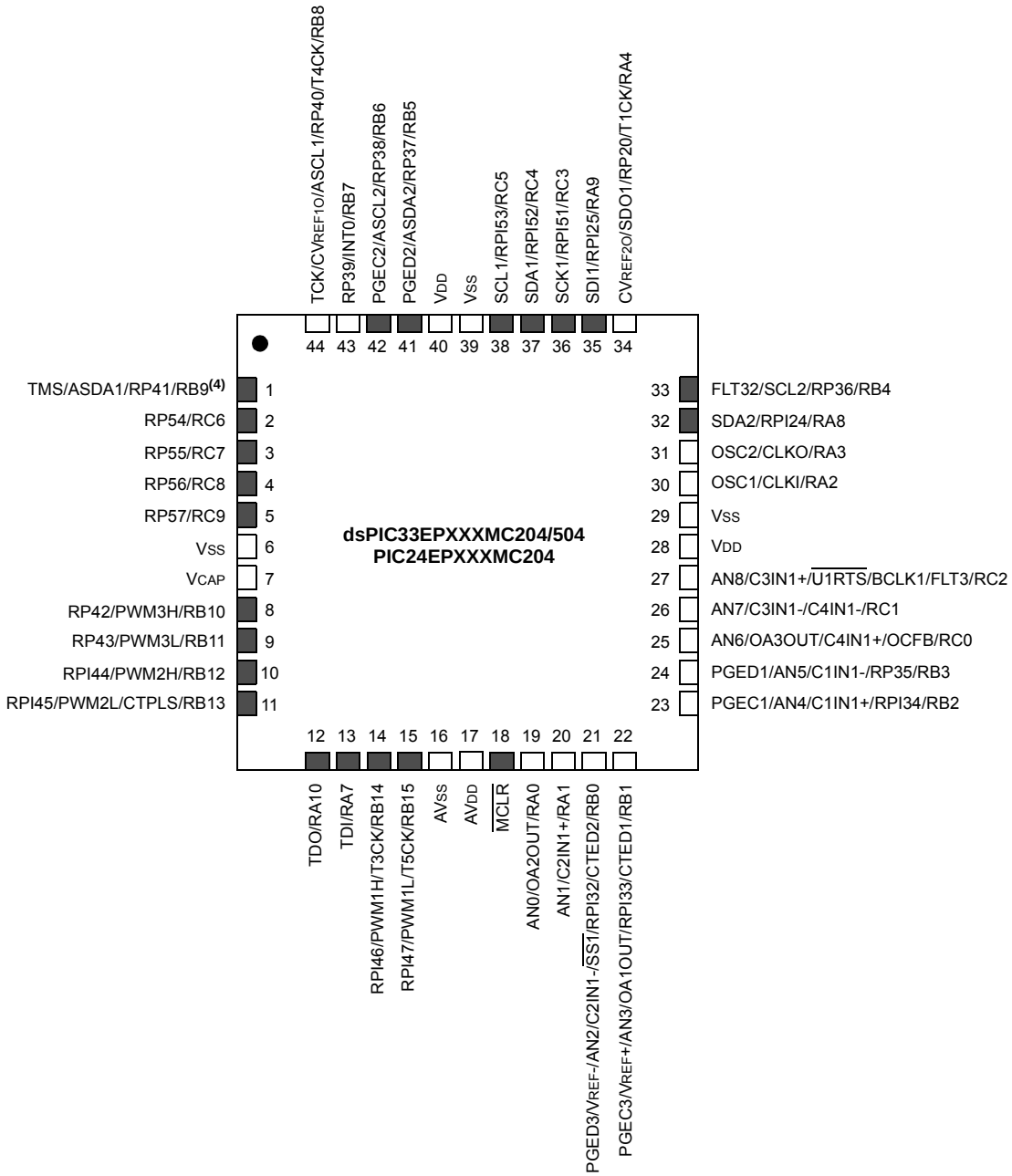
3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)

44-Pin QFN(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 2-5: SINGLE-PHASE SYNCHRONOUS BUCK CONVERTER

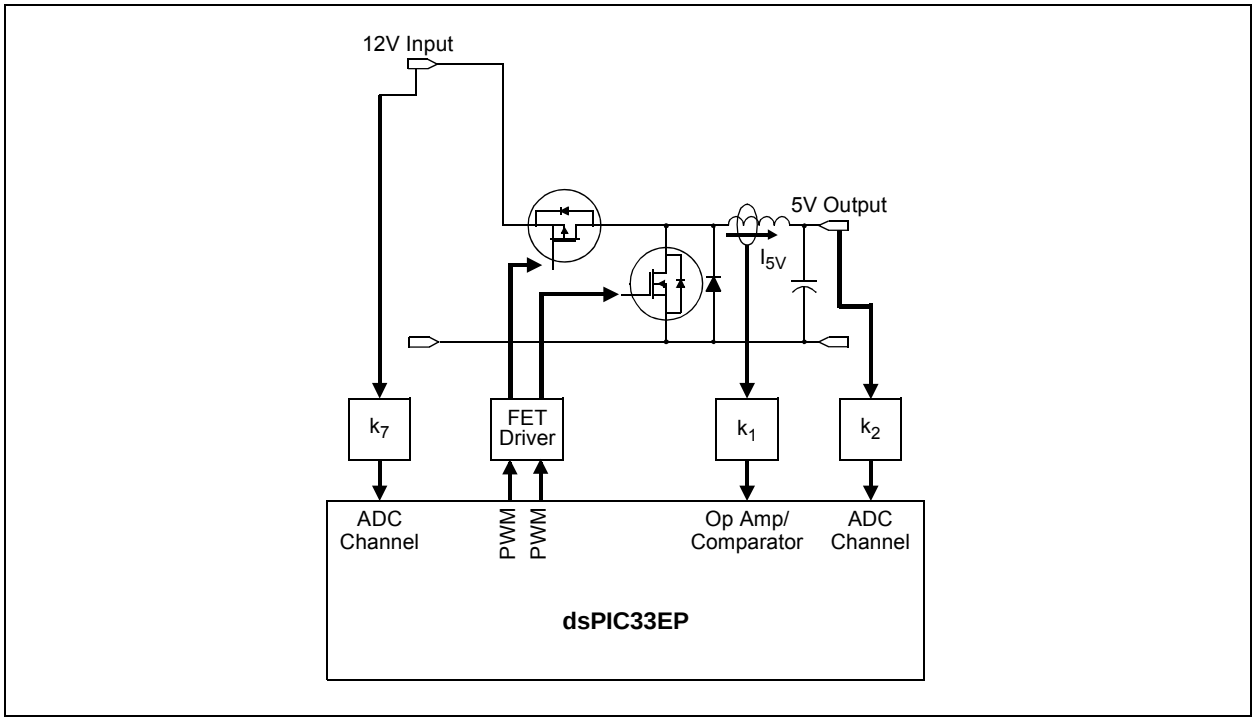


FIGURE 2-6: MULTIPHASE SYNCHRONOUS BUCK CONVERTER

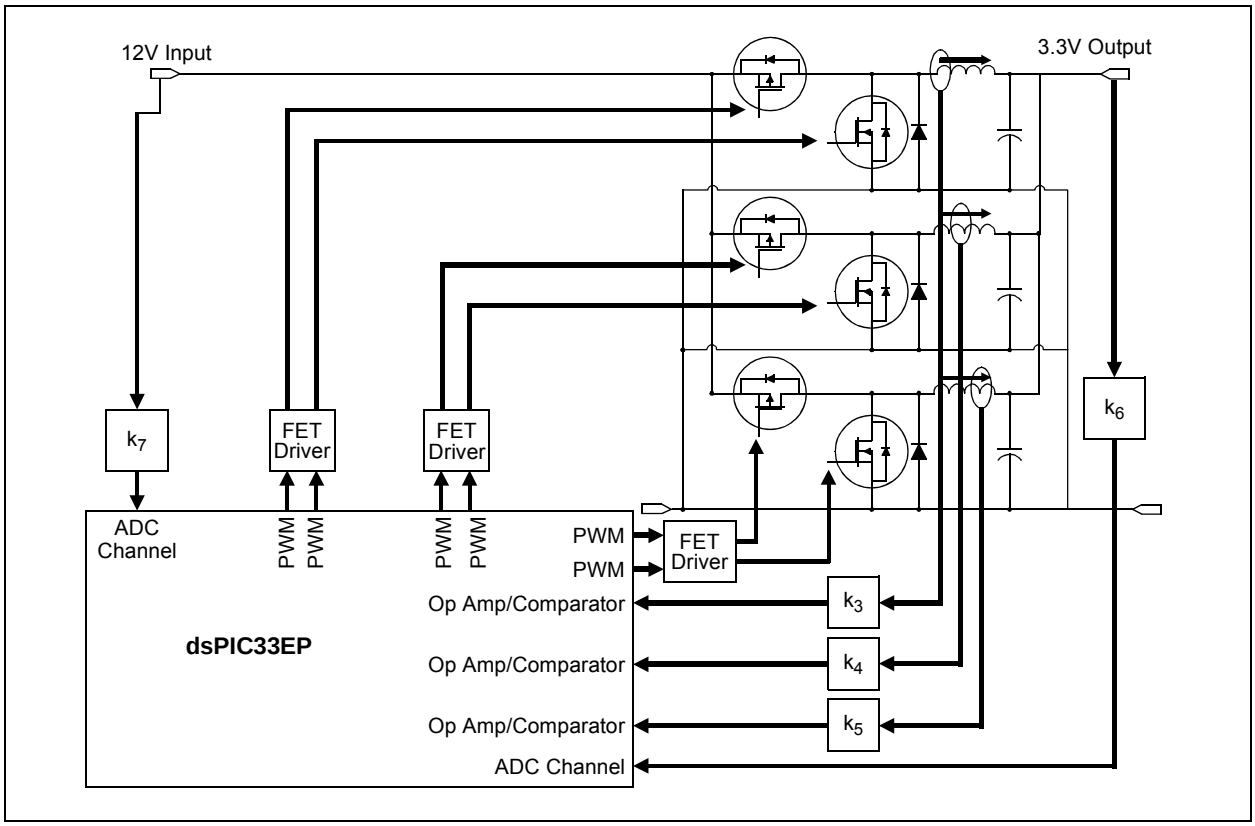


TABLE 4-19: SPI1 AND SPI2 REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SPI1STAT	0240	SPIEN	—	SPISIDL	—	—	SPIBEC<2:0>			SRMPT	SPIROV	SRXMPT	SISEL<2:0>			SPITBF	SPIRBF	0000
SPI1CON1	0242	—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE	SSEN	CKP	MSTEN	SPRE<2:0>			PPRE<1:0>		0000
SPI1CON2	0244	FRMEN	SPIFSD	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	FRMDLY	SPIBEN	0000
SPI1BUF	0248	SPI1 Transmit and Receive Buffer Register																0000
SPI2STAT	0260	SPIEN	—	SPISIDL	—	—	SPIBEC<2:0>			SRMPT	SPIROV	SRXMPT	SISEL<2:0>			SPITBF	SPIRBF	0000
SPI2CON1	0262	—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE	SSEN	CKP	MSTEN	SPRE<2:0>			PPRE<1:0>		0000
SPI2CON2	0264	FRMEN	SPIFSD	FRMPOL	—	—	—	—	—	—	—	—	—	—	—	FRMDLY	SPIBEN	0000
SPI2BUF	0268	SPI2 Transmit and Receive Buffer Register																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

NOTES:

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER(1) (CONTINUED)

bit 4 **Unimplemented:** Read as '0'

bit 3 **CF:** Clock Fail Detect bit(3)
- 1 = FSCM has detected clock failure
- 0 = FSCM has not detected clock failure

bit 2-1 **Unimplemented:** Read as '0'

bit 0 **OSWEN:** Oscillator Switch Enable bit
- 1 = Requests oscillator switch to selection specified by the NOSC<2:0> bits
- 0 = Oscillator switch is complete

Note 1: Writes to this register require an unlock sequence. Refer to **"Oscillator"** (DS70580) in the *"dsPIC33/PIC24 Family Reference Manual"* (available from the Microchip web site) for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

3: This bit should only be cleared in software. Setting the bit in software (= 1) will have the same effect as an actual oscillator failure and trigger an oscillator failure trap.

REGISTER 21-4: CxFCTRL: ECANx FIFO CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
DMABS2	DMABS1	DMABS0	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	FSA4	FSA3	FSA2	FSA1	FSA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **DMABS<2:0>:** DMA Buffer Size bits
111 = Reserved
110 = 32 buffers in RAM
101 = 24 buffers in RAM
100 = 16 buffers in RAM
011 = 12 buffers in RAM
010 = 8 buffers in RAM
001 = 6 buffers in RAM
000 = 4 buffers in RAM

bit 12-5 **Unimplemented:** Read as ‘0’

bit 4-0 **FSA<4:0>:** FIFO Area Starts with Buffer bits
11111 = Read Buffer RB31
11110 = Read Buffer RB30
•
•
•
00001 = TX/RX Buffer TRB1
00000 = TX/RX Buffer TRB0

23.0 10-BIT/12-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Analog-to-Digital Converter (ADC)"** (DS70621) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have one ADC module. The ADC module supports up to 16 analog input channels.

On ADC1, the AD12B bit (AD1CON1<10>) allows the ADC module to be configured by the user as either a 10-bit, 4 Sample-and-Hold (S&H) ADC (default configuration) or a 12-bit, 1 S&H ADC.

Note: The ADC module needs to be disabled before modifying the AD12B bit.

23.1 Key Features

23.1.1 10-BIT ADC CONFIGURATION

The 10-bit ADC configuration has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 1.1 Msps
- Up to 16 analog input pins
- Connections to three internal op amps
- Connections to the Charge Time Measurement Unit (CTMU) and temperature measurement diode
- Channel selection and triggering can be controlled by the Peripheral Trigger Generator (PTG)
- External voltage reference input pins
- Simultaneous sampling of:
  - Up to four analog input pins
  - Three op amp outputs
  - Combinations of analog inputs and op amp outputs
- Automatic Channel Scan mode
- Selectable conversion Trigger source
- Selectable Buffer Fill modes
- Four result alignment options (signed/unsigned, fractional/integer)
- Operation during CPU Sleep and Idle modes

23.1.2 12-BIT ADC CONFIGURATION

The 12-bit ADC configuration supports all the features listed above, with the exception of the following:

- In the 12-bit configuration, conversion speeds of up to 500 ksps are supported
- There is only one S&H amplifier in the 12-bit configuration; therefore, simultaneous sampling of multiple channels is not supported.

Depending on the particular device pinout, the ADC can have up to 16 analog input pins, designated AN0 through AN15. These analog inputs are shared with op amp inputs and outputs, comparator inputs, and external voltage references. When op amp/comparator functionality is enabled, or an external voltage reference is used, the analog input that shares that pin is no longer available. The actual number of analog input pins, op amps and external voltage reference input configuration depends on the specific device.

A block diagram of the ADC module is shown in Figure 23-1. Figure 23-2 provides a diagram of the ADC conversion clock period.

REGISTER 23-5: AD1CHS123: ADC1 INPUT CHANNEL 1, 2, 3 SELECT REGISTER (CONTINUED)

bit 0 **CH123SA:** Channel 1, 2, 3 Positive Input Select for Sample MUXA bit

In 12-bit mode (AD21B = 1), CH123SA is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
1(2)	OA1/AN3	OA2/AN0	OA3/AN6
0(1,2)	OA2/AN0	AN1	AN2

Note 1: AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

REGISTER 24-3: PTGBTE: PTG BROADCAST TRIGGER ENABLE REGISTER(1,2) (CONTINUED)

bit 4 **OC1CS:** Clock Source for OC1 bit
1 = Generates clock pulse when the broadcast command is executed
0 = Does not generate clock pulse when the broadcast command is executed

bit 3 **OC4TSS:** Trigger/Synchronization Source for OC4 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed

bit 2 **OC3TSS:** Trigger/Synchronization Source for OC3 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed

bit 1 **OC2TSS:** Trigger/Synchronization Source for OC2 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed

bit 0 **OC1TSS:** Trigger/Synchronization Source for OC1 bit
1 = Generates Trigger/Synchronization when the broadcast command is executed
0 = Does not generate Trigger/Synchronization when the broadcast command is executed

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

2: This register is only used with the PTGCTRL OPTION = 1111 Step command.

Most instructions are a single word. Certain double-word instructions are designed to provide all the required information in these 48 bits. In the second word, the 8 MSbs are '0's. If this second word is executed as an instruction (by itself), it executes as a NOP.

The double-word instructions execute in two instruction cycles.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true, or the Program Counter is changed as a result of the instruction, or a PSV or Table Read is performed, or an SFR register is read. In these cases, the execution takes multiple instruction cycles with the additional instruction cycle(s) executed as a NOP. Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or two-word instruction. Moreover, double-word moves require two cycles.

Note: For more details on the instruction set, refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157).

For more information on instructions that take more than one instruction cycle to execute, refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual"*, particularly the **"Instruction Flow Types"** section.

TABLE 28-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description
#text	Means literal defined by "text"
(text)	Means "content of text"
[text]	Means "the location addressed by text"
{ }	Optional field or operation
a ∈ {b, c, d}	a is selected from the set of values b, c, d
<n:m>	Register bit field
.b	Byte mode selection
.d	Double-Word mode selection
.S	Shadow register select
.w	Word mode selection (default)
Acc	One of two accumulators {A, B}
AWB	Accumulator write back destination address register ∈ {W13, [W13]+ = 2}
bit4	4-bit bit selection field (used in word addressed instructions) ∈ {0...15}
C, DC, N, OV, Z	MCU Status bits: Carry, Digit Carry, Negative, Overflow, Sticky Zero
Expr	Absolute address, label or expression (resolved by the linker)
f	File register address ∈ {0x0000...0x1FFF}
lit1	1-bit unsigned literal ∈ {0,1}
lit4	4-bit unsigned literal ∈ {0...15}
lit5	5-bit unsigned literal ∈ {0...31}
lit8	8-bit unsigned literal ∈ {0...255}
lit10	10-bit unsigned literal ∈ {0...255} for Byte mode, {0:1023} for Word mode
lit14	14-bit unsigned literal ∈ {0...16384}
lit16	16-bit unsigned literal ∈ {0...65535}
lit23	23-bit unsigned literal ∈ {0...8388608}; LSb must be '0'
None	Field does not require an entry, can be blank
OA, OB, SA, SB	DSP Status bits: ACCA Overflow, ACCB Overflow, ACCA Saturate, ACCB Saturate
PC	Program Counter
Slit10	10-bit signed literal ∈ {-512...511}
Slit16	16-bit signed literal ∈ {-32768...32767}
Slit6	6-bit signed literal ∈ {-16...16}
Wb	Base W register ∈ {W0...W15}
Wd	Destination W register ∈ { Wd, [Wd], [Wd++], [Wd--], [++Wd], [--Wd] }
Wdo	Destination W register ∈ { Wnd, [Wnd], [Wnd++], [Wnd--], [++Wnd], [--Wnd], [Wnd+Wb] }

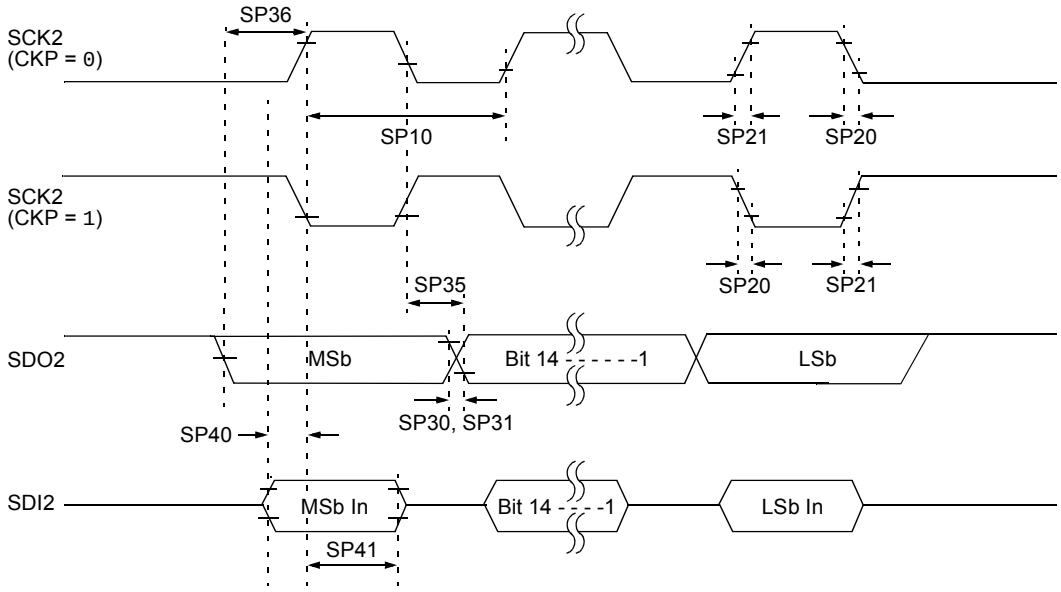
TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles(2)	Status Flags Affected
25	DAW	DAW	Wn	Wn = decimal adjust Wn	1	1	C
26	DEC	DEC	f	f = f – 1	1	1	C,DC,N,OV,Z
		DEC	f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC	Ws,Wd	Wd = Ws – 1	1	1	C,DC,N,OV,Z
27	DEC2	DEC2	f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2	f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2	Ws,Wd	Wd = Ws – 2	1	1	C,DC,N,OV,Z
28	DISI	DISI	#lit14	Disable Interrupts for k instruction cycles	1	1	None
29	DIV	DIV.S	Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD	Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U	Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD	Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
30	DIVF	DIVF	Wm,Wn(1)	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
31	DO	DO	#lit15,Expr(1)	Do code to PC + Expr, lit15 + 1 times	2	2	None
		DO	Wn,Expr(1)	Do code to PC + Expr, (Wn) + 1 times	2	2	None
32	ED	ED	Wm*Wm,Acc,Wx,Wy,Wxd(1)	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB
33	EDAC	EDAC	Wm*Wm,Acc,Wx,Wy,Wxd(1)	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB
34	EXCH	EXCH	Wns,Wnd	Swap Wns with Wnd	1	1	None
35	FBCL	FBCL	Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	C
36	FF1L	FF1L	Ws,Wnd	Find First One from Left (MSb) Side	1	1	C
37	FF1R	FF1R	Ws,Wnd	Find First One from Right (LSb) Side	1	1	C
38	GOTO	GOTO	Expr	Go to address	2	4	None
		GOTO	Wn	Go to indirect	1	4	None
		GOTO.L	Wn	Go to indirect (long address)	1	4	None
39	INC	INC	f	f = f + 1	1	1	C,DC,N,OV,Z
		INC	f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z
		INC	Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z
40	INC2	INC2	f	f = f + 2	1	1	C,DC,N,OV,Z
		INC2	f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z
		INC2	Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z
41	IOR	IOR	f	f = f .IOR. WREG	1	1	N,Z
		IOR	f,WREG	WREG = f .IOR. WREG	1	1	N,Z
		IOR	#lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z
		IOR	Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z
		IOR	Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z
42	LAC	LAC	Wso,#Slit4,Acc	Load Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
43	LNK	LNK	#lit14	Link Frame Pointer	1	1	SFA
44	LSR	LSR	f	f = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z
		LSR	Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z
		LSR	Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z
45	MAC	MAC	Wm*Wn,Acc,Wx,Wxd,Wy,Wyd,AWB(1)	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
		MAC	Wm*Wm,Acc,Wx,Wxd,Wy,Wyd(1)	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

FIGURE 30-16: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-35: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK2 Frequency	—	—	9	MHz	**(Note 3)**
SP20	TscF	SCK2 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK2 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 111 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-37: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of FP or 15	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	$\overline{SDO2}$ Data Output Valid after $\overline{SS2}$ Edge	—	—	50	ns	

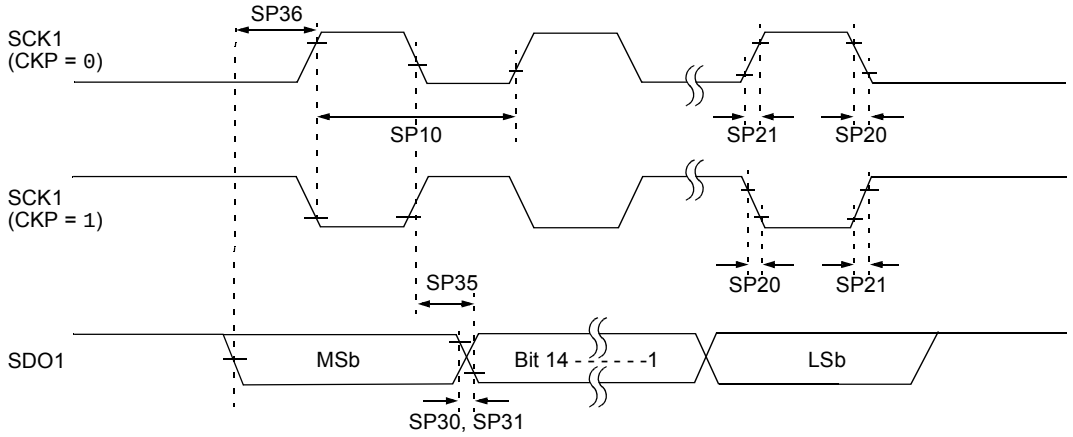
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-23: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-42: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	15	MHz	**(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-57: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)[1] Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or 3.0	—	Lesser of: VDD + 0.3 or 3.6	V	
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 2.5	—	AVDD	V	VREFH = VREF+ VREFL = VREF- **(Note 1)**
AD05a			3.0	—	3.6	V	VREFH = AVDD VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 2.5	V	**(Note 1)**
AD06a			0	—	0	V	VREFH = AVDD VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	2.5	—	3.6	V	VREF = VREFH - VREFL
AD08	IREF	Current Drain	— —	— —	10 600	μA μA	ADC off ADC on
AD09	IAD	Operating Current[2]	—	5	—	mA	ADC operating in 10-bit mode **(Note 1)**
			—	2	—	mA	ADC operating in 12-bit mode **(Note 1)**
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	200	Ω	Impedance to achieve maximum performance of ADC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameter is characterized but not tested in manufacturing.

TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C			
Parameter No.	Typical	Max	Units	Conditions		
Power-Down Current (I_{PD})						
HDC60e	1400	2500	μA	+150°C	3.3V	Base Power-Down Current **(Notes 1, 3)**
HDC61c	15	—	μA	+150°C	3.3V	Watchdog Timer Current: ΔI_{WDT} **(Notes 2, 4)**

Note 1: Base I_{PD} is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to V_{SS}. WDT, etc., are all switched off and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 31-5: DC CHARACTERISTICS: IDLE CURRENT (I_{IDLE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C			
Parameter No.	Typical	Max	Units	Conditions		
HDC44e	12	30	mA	+150°C	3.3V	40 MIPS

TABLE 31-6: DC CHARACTERISTICS: OPERATING CURRENT (I_{DD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C			
Parameter No.	Typical	Max	Units	Conditions		
HDC20	9	15	mA	+150°C	3.3V	10 MIPS
HDC22	16	25	mA	+150°C	3.3V	20 MIPS
HDC23	30	50	mA	+150°C	3.3V	40 MIPS

TABLE 31-7: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Parameter No.	Typical	Max	Doze Ratio	Units	Conditions		
HDC72a	24	35	1:2	mA	+150°C	3.3V	40 MIPS
HDC72f(1)	14	—	1:64	mA			
HDC72g(1)	12	—	1:128	mA			

Note 1: Parameters with Doze ratios of 1:64 and 1:128 are characterized, but are not tested in manufacturing.

NOTES:

Revision F (November 2012)

Removed “Preliminary” from data sheet footer.

Revision G (March 2013)

This revision includes the following global changes:

- changes “$\overline{\text{FLTx}}$” pin function to “FLTx” on all occurrences
- adds **Section 31.0 “High-Temperature Electrical Characteristics”** for high-temperature (+150°C) data

This revision also includes minor typographical and formatting changes throughout the text.

Other major changes are referenced by their respective section in Table A-5.

TABLE A-5: MAJOR SECTION UPDATES

Section Name	Update Description
Cover Section	• Changes internal oscillator specification to 1.0% • Changes I/O sink/source values to 12 mA or 6 mA • Corrects 44-pin VTLA pin diagram (pin 32 now shows as 5V tolerant)
Section 4.0 “Memory Organization”	• Deletes references to Configuration Shadow registers • Corrects the spelling of the JTAGIP and PTGWDTIP bits throughout • Corrects the Reset value of all IOCON registers as C000h • Adds footnote to Table 4-42 to indicate the absence of Comparator 3 in 28-pin devices
Section 6.0 “Resets”	• Removes references to cold and warm Resets, and clarifies the initial configuration of the device clock source on all Resets
Section 7.0 “Interrupt Controller”	• Corrects the definition of GIE as “Global Interrupt Enable” (not “General”)
Section 9.0 “Oscillator Configuration”	• Clarifies the behavior of the CF bit when cleared in software • Removes POR behavior footnotes from all control registers • Corrects the tuning range of the TUN<5:0> bits in Register 9-4 to an overall range ±1.5%
Section 13.0 “Timer2/3 and Timer4/5”	• Clarifies the presence of the ADC Trigger in 16-bit Timer3 and Timer5, as well as the 32-bit timers
Section 15.0 “Output Compare”	• Corrects the first trigger source for SYNCSEL<4:0> (OCxCON2<4:0>) as OCxRS match
Section 16.0 “High-Speed PWM Module”	• Clarifies the source of the PWM interrupts in Figure 16-1 • Corrects the Reset states of IOCONx<15:14> in Register 16-13 as ‘11’
Section 17.0 “Quadrature Encoder Interface (QEI) Module”	• Clarifies the operation of the IMV<1:0> bits (QEICON<9:8>) with updated text and additional notes • Corrects the first prescaler value for QFVDIV<2:0> (QEI1OC<13:11>), now 1:128
Section 23.0 “10-Bit/12-Bit Analog-to-Digital Converter (ADC)”	• Adds note to Figure 23-1 that Op Amp 3 is not available in 28-pin devices • Changes “sample clock” to “sample trigger” in AD1CON1 (Register 23-1) • Clarifies footnotes on op amp usage in Registers 23-5 and 23-6
Section 25.0 “Op Amp/ Comparator Module”	• Adds Note text to indicate that Comparator 3 is unavailable in 28-pin devices • Splits Figure 25-1 into two figures for clearer presentation (Figure 25-1 for Op amp/ Comparators 1 through 3, Figure 25-2 for Comparator 4). Subsequent figures are renumbered accordingly. • Corrects reference description in xxxxx (now (AV_{DD} + AV_{SS})/2) • Changes CMSTAT<15> in Register 25-1 to “PSIDL”
Section 27.0 “Special Features”	• Corrects the addresses of all Configuration bytes for 512 Kbyte devices

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